

### REMARKS

By the present amendment, claim 1 has been amended to more clearly recite the present invention. No new matter and no new issues have been raised by way of the present amendment. Claim 1 is the only pending independent claim.

Applicant notes with appreciation the Examiner's indication that claims 2-6 are allowable over the art of record.

Claims 1-6 are presented to the Examiner for further prosecution on the merits.

In the outstanding Office action mailed October 19, 2004, the Examiner rejected claim 1 under 35 U.S.C. § 102(a) as anticipated by Paul A. Kohl et al., "Wafer-Level Packaging Addresses Chip-to-Module Interconnections," April 2001 ("the Kohl et al. reference"). Applicants respectfully submit that claim 1 clearly defines the present invention over the Kohl et al. reference for at least the reasons set forth below.

Claim 1, as amended, recites a structure for providing resilient interconnections in a wafer level package, comprising a conductive pad that *directly* overlays an air space, wherein at least a portion of the air space extends laterally beyond the conductive pad. The Kohl et al. reference, on the other hand, does not have a conductive pad (metal lead) that directly overlays an air space (buried air cavity). There is nothing in the Kohl et al. reference that would teach or suggest the present invention as claimed in claim 1 wherein a conductive pad directly overlays an air space with at least a portion of the air space extending laterally beyond the conductive pad.

Accordingly, applicant respectfully submits that the Kohl et al. reference fails to disclose the present invention as claimed in claim 1, and that the rejection of claim 1 under 35 U.S.C. § 102(a) based on the Kohl et al. reference is traversed.

If the Examiner believes that additional discussions or information might advance the prosecution of the instant application, the Examiner is invited to contact the undersigned at the telephone number listed below to expedite resolution of any outstanding issues.

In view of the foregoing amendments and remarks, favorable reconsideration of this application is earnestly solicited, and a notice of allowance of pending claims 1-6 is hereby respectfully solicited.

Respectfully submitted,

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**PETITION and**  
**DEPOSIT ACCOUNT CHARGE AUTHORIZATION**

This document and any concurrently filed papers are believed to be timely. Should any extension of the term be required, applicant hereby petitions the Director for such extension and requests that any applicable petition fee be charged to Deposit Account No. 50-1645.

If fee payment is enclosed, this amount is believed to be correct. However, the Director is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-1645.

Any additional fee(s) necessary to effect the proper and timely filing of the accompanying-papers may also be charged to Deposit Account No. 50-1645.